

PCN Number:	20181106000		PCN Date:	Dec. 13, 2018						
Title:	TPS65311QRVJRQ1 Tester Platform and Test site change									
Customer Contact:	PCN Manager		Dept:	Quality Services						
Proposed 1st Ship Date:	Jun 13, 2019									
Change Type:										
☐	Assembly Site	☐	Design	☐						
☐	Assembly Process	☐	Data Sheet	☐						
☐	Assembly Materials	☐	Part number change	☐						
☐	Mechanical Specification	☒	Test Site	☐						
☐	Packing/Shipping/Labeling	☒	Test Process	☐						
				☐						
				Wafer Bump Site						
				Wafer Bump Material						
				Wafer Bump Process						
				Wafer Fab Site						
				Wafer Fab Materials						
				Wafer Fab Process						
PCN Details										
Description of Change:										
Texas Instruments Incorporated is announcing the qualification of TPS65311QRVJRQ1 conversion from Tester Platform IFLEX to ETS800 and Test site transfer from TI Malaysia to TI Taiwan.										
<table border="1"> <thead> <tr> <th>From</th> <th>To</th> </tr> </thead> <tbody> <tr> <td>IFLEX x4</td> <td>ETS800 x16</td> </tr> <tr> <td>TI Malaysia</td> <td>TI Taiwan</td> </tr> </tbody> </table>					From	To	IFLEX x4	ETS800 x16	TI Malaysia	TI Taiwan
From	To									
IFLEX x4	ETS800 x16									
TI Malaysia	TI Taiwan									
Reason for Change:										
Current test solution is capacity constrained.										
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):										
None.										
Changes to product identification resulting from this PCN:										
None.										
Product Affected:										
TPS65311QRVJRQ1										

TPS65311QRVJRQ1 Conversion to ETS800

TI Information – Selective Disclosure

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Conversion Summary

- FT flow for TPS65311 (no change to this flow is proposed)
 - FT1 @ 25C → FT2 @ 125C
- Current test solution is x4 site on Teradyne FLEX
- Proposed test solution is x16 sites on Teradyne ETS800
- All test application circuitry to be the same as FLEX
- All tests are performed on ETS800 (no change in test plan)
- Checkout process using MSA Tester Platform Conversion Guide, which is inclusive of all RelCon requirements
- Critical checkout results:
 - All tests performed with the same limits on both test solutions
 - RWE package of this device already RTP'ed in TITL
 - Same Die
 - Same Test Hardware
 - Same Test Program
 - 1 Lot Underkill study performed
 - 100% of failures from FLEX also failed on ETS800

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FLEX <> ETS800 Correlation Data– TPS65311 Conversion

TITL SWR Q165311QRVJRQ1 LOT#8422695										
FT1 25C ETS800 x16 (PGM EF723011 with FT mode)										
	USE	PASS	CONTY	PARA	HBin9	PMI	OTHER	O/S YIELD	FT YIELD	Comments
FT1 SUMMARY	2879	2866	5	8				0.17%	99.55%	FT1 Rejects Lot#8451843
FT2 125C ETS800 x16 (PGM EF723011 with FT mode)										
	USE	PASS	CONTY	PARA	HBin9	PMI	OTHER	O/S YIELD	FT YIELD	Comments
FT2 SUMMARY	2866	2865		1				0.00%	99.97%	FT2 Rejects Lot#8451851
TIM SWR Q65311QRVJRQ1Z LOT#8540523										
FT1 25C IFLEX x4 (PGM PF192624 with QA(FT1) mode)										
	USE	PASS	CONTY	PARA	HBin9	PMI	OTHER	O/S YIELD	FT YIELD	Comments
FT1 SUMMARY	2865	2865	0	0				0.00%	100.00%	UNDERKILL 0
TAI FT1 REJECTS	13	1	5	7				38.46%	7.69%	OVERKILL 1
FT2 125C IFLEX x4 (PGM PF192624 with QA(FT2) mode)										
	USE	PASS	CONTY	PARA	HBin9	PMI	OTHER	O/S YIELD	FT YIELD	Comments
FT2 SUMMARY	2865	2865	0	0				0.00%	100.00%	UNDERKILL 0
TAI FT2 REJECTS	1	1	0	0				0.00%	100.00%	OVERKILL 1

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For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com